# NPN Silicon Planar Epitaxial Transistor

This NPN Silicon Epitaxial transistor is designed for use in linear and switching applications. The device is housed in the SOT-223 package which is designed for medium power surface mount applications.

### **Features**

- PNP Complement is PZT2907AT1
- The SOT-223 Package Can be Soldered Using Wave or Reflow
- SOT-223 Package Ensures Level Mounting, Resulting in Improved Thermal Conduction, and Allows Visual Inspection of Soldered Joints
- The Formed Leads Absorb Thermal Stress During Soldering, Eliminating the Possibility of Damage to the Die
- Available in 12 mm Tape and Reel
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant\*

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	40	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	75	Vdc
Emitter-Base Voltage (Open Collector)	V <sub>EBO</sub>	6.0	Vdc
Collector Current	I <sub>C</sub>	600	mAdc
Total Power Dissipation up to T <sub>A</sub> = 25°C (Note 1)	P <sub>D</sub>	1.5	W
Storage Temperature Range	T <sub>stg</sub>	- 65 to +150	°C
Junction Temperature	TJ	150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Device mounted on an epoxy printed circuit board 1.575 inches x 1.575 inches x 0.059 inches; mounting pad for the collector lead min. 0.93 inches<sup>2</sup>.

### THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	83.3	°C/W
Lead Temperature for Soldering, 0.0625" from case Time in Solder Bath	T <sub>L</sub>	260 10	°C Sec

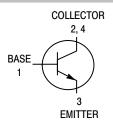


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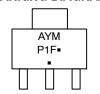
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# SOT-223 PACKAGE NPN SILICON TRANSISTOR SURFACE MOUNT





### **MARKING DIAGRAM**



A = Assembly Location

Y = Year M = Month Code ■ = Pb-Free Package

(Note: Microdot may be in either location)

# ORDERING INFORMATION

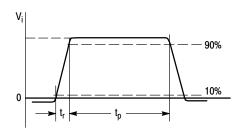
Device	Package	Shipping <sup>†</sup>
PZT2222AT1G	SOT-223 (Pb-Free)	1,000 Tape & Reel
SPZT2222AT1G	SOT-223 (Pb-Free)	1,000 Tape & Reel
PZT2222AT3G	SOT-223 (Pb-Free)	4,000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Collector-Emitter Cutoff Current (V <sub>CE</sub> = 60 Vdc, V <sub>BE</sub> = - 3.0 Vdc)   I <sub>CEX</sub>   -   10   nAdc		Characteristic	Symbol	Min	Max	Unit
Collector - Base Breakdown Voltage ((c = 10 µAdc, l <sub>E</sub> = 0)	OFF CHARACTER	RISTICS				
Emitter-Base Breakdown Voltages (tg = 10 µAdo, tg = 0)	Collector-Emitter	Breakdown Voltage (I <sub>C</sub> = 10 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	40	-	Vdc
Base-Emitter Cutoff Current (V <sub>CE</sub> = 60 Vdc, V <sub>BE</sub> = −3.0 Vdc)   I <sub>BEX</sub>	Collector-Base B	reakdown Voltage (I <sub>C</sub> = 10 μAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	75	-	Vdc
Collector-Emitter Cutoff Current (V <sub>CE</sub> = 60 Vdc, V <sub>BE</sub> = − 3.0 Vdc)         I <sub>CEX</sub> −         10         nAdd           Emitter-Base Cutoff Current (V <sub>CB</sub> = 3.0 Vdc, I <sub>C</sub> = 0)         I <sub>EBO</sub> −         100         nAdd           Collector-Base Cutoff Current (V <sub>CB</sub> = 0.0 Vdc, I <sub>E</sub> = 0)         I <sub>CBO</sub> −         10         nAdd           V(CB = 60 Vdc, I <sub>E</sub> = 0, T <sub>A</sub> = 1.25°C)         0         −         10         nAdd           DC Current Gain (I <sub>C</sub> = 1.0 Vdc) (I <sub>C</sub> = 1.0 Vdc)         50         −         10         nAdd           I(C = 0.1 mAdc, V <sub>CE</sub> = 10 Vdc) (I <sub>C</sub> = 1.0 Vdc) (I <sub>C</sub> = 10 Mdc, V <sub>CE</sub> = 10 Vdc)         50         −         −           I(C = 1.6 mAdc, V <sub>CE</sub> = 1.0 Vdc) (I <sub>C</sub> = 1.0 Vdc) (I <sub>C</sub> = 1.0 Vdc) (I <sub>C</sub> = 1.0 Vdc)         50         −         −           I(C = 150 mAdc, V <sub>CE</sub> = 1.0 Vdc) (I <sub>C</sub> = 1.0 Vdc) (I <sub>C</sub> = 500 mAdc, I <sub>D</sub> = 1.5 mAdc)         7         −         −         0.3         −           I(C = 150 mAdc, V <sub>CE</sub> = 1.0 Vdc) (I <sub>C</sub> = 1.0 Kdc) (I <sub>C</sub> = 1.0 Kdc) (I <sub>C</sub> = 1.0 Kdc) (I <sub>C</sub> = 1.0 Mdc, I <sub>D</sub> = 1.0 Kdc) (I <sub>C</sub> = 1.0 Mdc, I <sub>D</sub> = 1.0 Kdc) (I <sub>C</sub> = 1.0 Mdc, I <sub>D</sub> = 1.0 Kdc) (I <sub>C</sub> = 1.0 Mdc, I <sub>D</sub> = 1.0 Kdc) (I <sub>C</sub> = 1.0 Mdc, I <sub>C</sub> = 1.0 Mdc, I <sub>D</sub> = 1.0 Kdc) (I <sub>C</sub> = 1.0 Mdc, I <sub>D</sub> = 1.0	Emitter-Base Bre	akdown Voltage (I <sub>E</sub> = 10 μAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	6.0	_	Vdc
Emitter - Base Cutoff Current (V <sub>EB</sub> = 3.0 Vdc, I <sub>C</sub> = 0)	Base-Emitter Cut	off Current (V <sub>CE</sub> = 60 Vdc, V <sub>BE</sub> = - 3.0 Vdc)	I <sub>BEX</sub>	-	20	nAdc
Collector-Base Cutoff Current   V(Se) = 60 Vdc,   E = 0)   Ta = 125°C)	Collector-Emitter	Cutoff Current (V <sub>CE</sub> = 60 Vdc, V <sub>BE</sub> = - 3.0 Vdc)	I <sub>CEX</sub>	-	10	nAdc
Voc = 60 Vdc,  c = 0   T_A = 125°C)	Emitter-Base Cut	off Current (V <sub>EB</sub> = 3.0 Vdc, I <sub>C</sub> = 0)	I <sub>EBO</sub>	-	100	nAdd
DC Current Gain   C   C   C   1 mAdc, V <sub>CE</sub> = 10 Vdc   C   C   1 mAdc, V <sub>CE</sub> = 10 Vdc   C   C   1 mAdc, V <sub>CE</sub> = 10 Vdc   C   C   1 mAdc, V <sub>CE</sub> = 10 Vdc   C   C   1 mAdc, V <sub>CE</sub> = 10 Vdc   C   C   1 mAdc, V <sub>CE</sub> = 10 Vdc   C   C   1 mAdc, V <sub>CE</sub> = 10 Vdc   C   C   1 mAdc, V <sub>CE</sub> = 10 Vdc   C   C   1 mAdc, V <sub>CE</sub> = 10 Vdc   C   C   S   MAdc, V <sub>CE</sub> = 10 Vdc   C   S   MAdc, V <sub>CE</sub> = 10 MAdc, V <sub>CE</sub> = 20 Vdc, V <sub>CE</sub> = 10 MAdc, V <sub>CE</sub> = 20 Vdc, V <sub>CE</sub> = 10 MAdc, V <sub>CE</sub> = 20 Vdc, V <sub>CE</sub> = 10 MAdc, V <sub>CE</sub> =	$(V_{CB} = 60 \text{ Vdc},$	I <sub>E</sub> = 0)	Ісво	- -		nAdc μAdc
(I <sub>C</sub> = 0.1 mAdc, V <sub>CE</sub> = 10 Vdc)   C = 10 Mdc, V <sub>CE</sub> = 10 Vdc)   C = 10 mAdc, V <sub>CE</sub> = 10 Vdc)   S = 10 Vdc, V <sub>CE</sub> = 10 Vdc, V <sub>CE</sub> = 1.0 Vdc)   S = 10 Vdc, V <sub>CE</sub> = 1.0 Vdc, V <sub>CE</sub> = 1.0 Vdc)   S = 10 Vdc, V <sub>CE</sub> = 1.0 Vdc)   S = 10 Vdc, V <sub>CE</sub> = 1.0 Vdc)   S = 10 Vdc, V <sub>CE</sub> = 1.0 Vdc)   S = 10 Vdc, V <sub>CE</sub> = 1.0 Vdc)   S = 10 Vdc, V <sub>CE</sub> = 1.0 Vdc)   S = 10 Vdc, V <sub>CE</sub> = 1.0 Vdc)   S = 10 Vdc, V <sub>CE</sub> = 1.0 Vdc, V <sub>CE</sub> = 1.0 Vdc)   S = 10 Vdc, V <sub>CE</sub> = 1.0 Vdc, V <sub>CE</sub> = 1.0 Vdc)   S = 10 Vdc, V <sub>CE</sub> = 1.0 Vdc, V <sub>CE</sub> = 1.	ON CHARACTER	ISTICS	·			
(I <sub>C</sub> = 150 mAdc, I <sub>B</sub> = 15 mAdc)	$(I_{C} = 0.1 \text{ mAdc}, \ (I_{C} = 1.0 \text{ mAdc}, \ (I_{C} = 10 \text{ mAdc}, \ (I_{C} = 10 \text{ mAdc}, \ (I_{C} = 150 \text{ mAdc}, \ (I_{C} = 150 \text{ mAdc})$	$V_{CE} = 10 \text{ Vdc}$ ) $V_{CE} = 10 \text{ Vdc}$ ) $V_{CE} = 10 \text{ Vdc}$ , $T_{A} = -55^{\circ}\text{C}$ ) $V_{CE} = 10 \text{ Vdc}$ ) $V_{CE} = 1.0 \text{ Vdc}$ )	h <sub>FE</sub>	50 70 35 100 50	- 300 -	-
(I <sub>C</sub> = 150 MAdc, I <sub>B</sub> = 15 MAdc)       0.6       1.2         (I <sub>C</sub> = 500 MAdc, I <sub>B</sub> = 50 mAdc)       h <sub>IB</sub> 2.0         Input Impedance       (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 1.0 mAdc, f = 1.0 kHz)       2.0       8.0         (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 10 mAdc, f = 1.0 kHz)       h <sub>re</sub> -       8.0x10 <sup>-4</sup> Voltage Feedback Ratio       h <sub>re</sub> -       8.0x10 <sup>-4</sup> -         (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 10 mAdc, f = 1.0 kHz)       -       4.0x10 <sup>-4</sup> -         Small-Signal Current Gain       (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 1.0 mAdc, f = 1.0 kHz)       50       300       -         (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 1.0 mAdc, f = 1.0 kHz)       50       30       375       -         Output Admittance       h <sub>Oe</sub> 5.0       35       25       200         Noise Figure (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 1.0 mAdc, f = 1.0 kHz)       F       -       4.0       dB         DYNAMIC CHARACTERISTICS         Current-Gain - Bandwidth Product       f       T       300       -         (I <sub>C</sub> = 20 mAdc, V <sub>CE</sub> = 20 Vdc, f = 100 MHz)       C <sub>C</sub> -       8.0       pF         Diput Capacitance (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 0, f = 1.0 MHz)       C <sub>C</sub> -       8.0       pF         SWITCHING TIMES (T <sub>A</sub> =	$(I_C = 150 \text{ mAdd})$	s, I <sub>B</sub> = 15 mAdc)	V <sub>CE(sat)</sub>	- -		Vdc
Voc   10 Vdc,   C   1.0 mAdc, f   1.0 kHz    2.0   0.25   1.25     Voltage Feedback Ratio   Voc   10 mAdc, f   1.0 kHz    - 8.0x10^{-4}   - 4.0x10^{-4}     Small – Signal Current Gain   Voc   10 Vdc,   C   10 mAdc, f   1.0 kHz    - 4.0x10^{-4}     Small – Signal Current Gain   Voc   10 Vdc,   C   10 mAdc, f   1.0 kHz    - 4.0x10^{-4}     Small – Signal Current Gain   Voc   10 Vdc,   C   10 mAdc, f   1.0 kHz    - 50   300   75   375     Output Admittance   Voc   10 Vdc,   C   10 mAdc, f   1.0 kHz    - 4.0	$(I_C = 150 \text{ mAdd})$	s, I <sub>B</sub> = 15 mAdc)	V <sub>BE(sat)</sub>			Vdc
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	(V <sub>CE</sub> = 10 Vdc,	-	h <sub>ie</sub>			kΩ
(V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 1.0 mAdc, f = 1.0 kHz)       50       300         (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 10 mAdc, f = 1.0 kHz)       75       375         Output Admittance       hoe       5.0       35         (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 1.0 mAdc, f = 1.0 kHz)       5.0       35         Noise Figure (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 100 μAdc, f = 1.0 kHz)       F       -       4.0       dB         DYNAMIC CHARACTERISTICS         Current-Gain - Bandwidth Product (I <sub>C</sub> = 20 mAdc, V <sub>CE</sub> = 20 Vdc, f = 100 MHz)       fT       300       -       MHz         Output Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)       Cc       -       8.0       pF         Input Capacitance (V <sub>CB</sub> = 0.5 Vdc, I <sub>C</sub> = 0, f = 1.0 MHz)       Ce       -       25       pF         SWITCHING TIMES (T <sub>A</sub> = 25°C)         Delay Time       (V <sub>CC</sub> = 30 Vdc, I <sub>C</sub> = 150 mAdc, I <sub>B(off)</sub> = 0.5 Vdc)       td       -       10       ns         Rise Time       (V <sub>CC</sub> = 30 Vdc, I <sub>C</sub> = 150 mAdc, I <sub>C</sub> = 150 mAdc, I <sub>B(off)</sub> = 15 mAdc)       ts       -       225       ns	(V <sub>CE</sub> = 10 Vdc,	$I_C = 1.0 \text{ mAdc, } f = 1.0 \text{ kHz}$	h <sub>re</sub>			-
	(V <sub>CE</sub> = 10 Vdc,	$I_C = 1.0 \text{ mAdc, } f = 1.0 \text{ kHz})$	h <sub>fe</sub>			-
Current-Gain - Bandwidth Product ( $I_C = 20 \text{ mAdc}$ , $V_{CE} = 20 \text{ Vdc}$ , $f = 100 \text{ MHz}$ )  Output Capacitance ( $V_{CB} = 10 \text{ Vdc}$ , $I_E = 0$ , $f = 1.0 \text{ MHz}$ )  Expected by the control of t	(V <sub>CE</sub> = 10 Vdc,	$I_C = 1.0 \text{ mAdc, } f = 1.0 \text{ kHz}$	h <sub>oe</sub>			μmho
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Noise Figure (V <sub>Cl</sub>	$E = 10 \text{ Vdc}, I_C = 100 \mu\text{Adc}, f = 1.0 \text{ kHz}$	F	-	4.0	dB
	DYNAMIC CHARA	ACTERISTICS				
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			f <sub>T</sub>	300	-	MHz
	Output Capacitan	ce (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>c</sub>		8.0	pF
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Input Capacitance	e (V <sub>EB</sub> = 0.5 Vdc, I <sub>C</sub> = 0, f = 1.0 MHz)	C <sub>e</sub>	-	25	pF
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	SWITCHING TIME	<b>S</b> (T <sub>A</sub> = 25°C)				
Rise Time Figure 1 $t_r$ - 25  Storage Time $(V_{CC} = 30 \text{ Vdc}, I_C = 150 \text{ mAdc}, I_{B(on)} = I_{B(off)} = 15 \text{ mAdc})$	Delay Time		t <sub>d</sub>	-	10	ns
Storage Time $(V_{CC} = 30 \text{ Vdc}, I_C = 150 \text{ mAdc}, I_{S} - 225 \text{ ns}$ $I_{B(on)} = I_{B(off)} = 15 \text{ mAdc})$	Rise Time		t <sub>r</sub>	_	25	
$I_{B(on)} = I_{B(off)} = 15 \text{ mAdc}$	Storage Time	<u> </u>		_	225	ns
	Fall Time		t <sub>f</sub>	_	60	



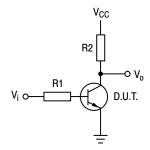
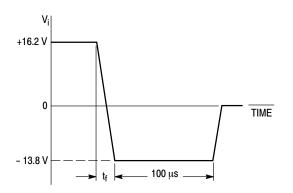


Figure 1. Input Waveform and Test Circuit for Determining Delay Time and Rise Time

 $V_{i}$  = - 0.5 V to +9.9 V,  $V_{CC}$  = +30 V, R1 = 619  $\Omega,$  R2 = 200  $\Omega.$ 

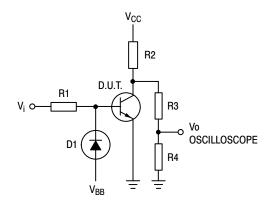


Figure 2. Input Waveform and Test Circuit for Determining Storage Time and Fall Time

### **TYPICAL CHARACTERISTICS**

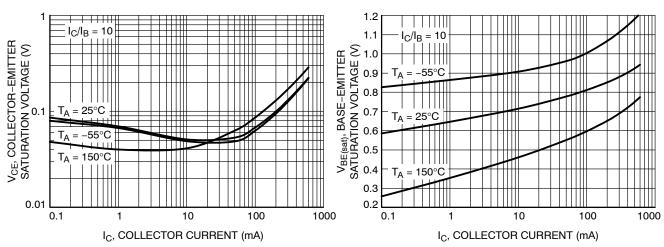


Figure 3. Collector Emitter Saturation Voltage vs. Collector Current

Figure 4. Base Emitter Saturation Voltage vs.
Collector Current

### **TYPICAL CHARACTERISTICS**

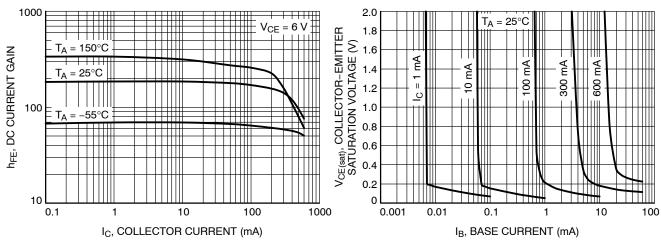


Figure 5. DC Current Gain vs. Collector Current

Figure 6. Saturation Region

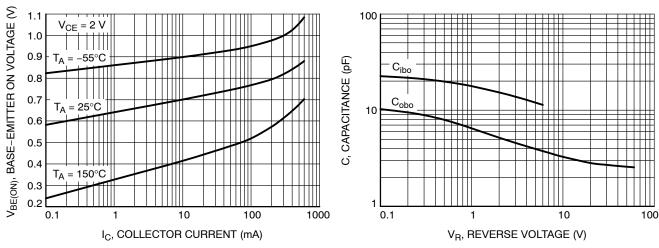


Figure 7. Base-Emitter Turn-On Voltage vs.
Collector Current

Figure 8. Capacitance

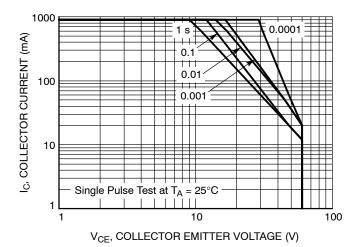
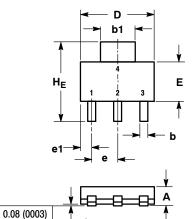
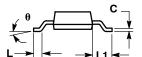


Figure 9. Safe Operating Area

#### PACKAGE DIMENSIONS

### SOT-223 (TO-261) CASE 318E-04 ISSUE N





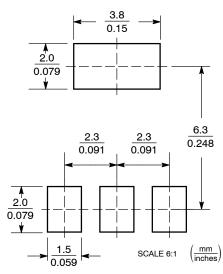
DIMENSIONING AND TOLERANCING PER ASME Y14.5M,

1.	1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,					
199	1994.					
2	2. CONTROLLING DIMENSION: INCH.					
	М	ILLIMETE	RS	INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
С	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L	0.20			0.008		
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	-	10°	0°	-	10°

STYLE 1: PIN 1. BASE

- COLLECTOR EMITTER 2.
- COLLECTOR

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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